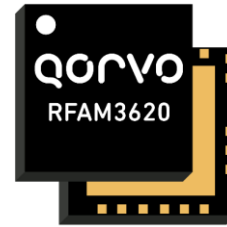
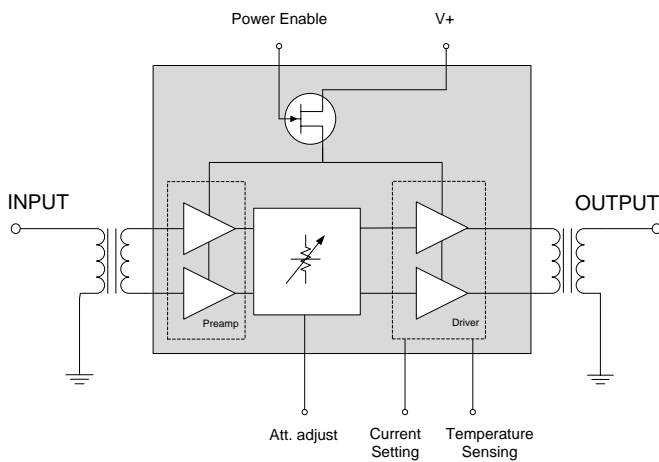


### Product Description

The RFAM3620 is an Integrated Edge QAM Amplifier Module. The part employs GaAs pHEMT die, GaAs MESFET die, a 20 dB range variable attenuator and a power enable feature, has high output capability, and is operated from 45 MHz to 1218 MHz. It provides excellent linearity and superior return loss performance with low noise and optimal reliability.

### Functional Block Diagram



21 pin, 11.0 mm x 11.0 mm x 1.375 mm package

### Product Features

- Excellent Linearity
- Extremely High Output Capability
- Voltage Controlled Attenuator
- Power Enable Feature
- Extremely Low Distortion
- Optimal Reliability
- Low Noise
- Unconditionally Stable Under all Terminations
- 36 dB Min Gain at 1218 MHz
- 510 mA Typical at 12 VDC
- Temperature sensing feature

### Applications

- Head End Equipment
- 45 – 1218 MHz Downstream Edge QAM RF Modulators

### Ordering Information

| Part No.         | Description                      |
|------------------|----------------------------------|
| RFAM3620SB       | Sample bag 5 pcs                 |
| RFAM3620SR       | 7" Reel with 100 pcs             |
| RFAM3620TR7      | 7" Reel with 250 pcs             |
| RFAM3620PCBA-410 | Fully assembled Evaluation Board |

## Absolute Maximum Ratings

| Parameter  | Value / Range  |
|--|----------------|
| DC Supply over-voltage (5 minutes)               | +14 V          |
| Storage Temperature                              | -40 to 100 °C  |
| Operating Mounting Base Temperature              | -30 to 110 °C  |
| Moisture Sensitivity Level<br>IPC/JEDEC J-STD-20 | MSL 3 @ 260 °C |

Operation of this device outside the parameter ranges given above may cause permanent damage.

## Electrical Specifications – part 1

| Parameter                   | Conditions (V+=12V, TMB=30°C, ZS=ZL=75Ω, ATT=0dB)            | Min    | Typ          | Max  | Units |
|-----------------------------|--|--------|--------------|------|-------|
| Operational Frequency Range | –  | 45     | –            | 1218 | MHz   |
| Current (I <sub>DD</sub> )  | –  |        | 510          | 550  | mA    |
| Gain                        | f <sub>o</sub> = 45 MHz                                      |        | 35.5         |      | dB    |
| Gain                        | f <sub>o</sub> = 1218 MHz                                    | 36.0   | 37.0         | 38.0 |       |
| Gain Slope                  | 45 to 1218 MHz <sup>[1]</sup>                                | 0.5    | 1.0          | 2.5  |       |
| Gain Flatness               | 45 to 1218 MHz   |        | 0.5          | 1.0  |       |
| Input Return Loss           | f <sub>o</sub> = 45 to 160 MHz                               | 18     |              | –    | dB    |
|                             | f <sub>o</sub> = 160 to 1003 MHz                             | 15     |              | –    |       |
|                             | f <sub>o</sub> = 1003 to 1218 MHz                            | 15     |              | –    |       |
| Output Return Loss          | f <sub>o</sub> = 45 to 160 MHz                               | 18     |              | –    | dB    |
|                             | f <sub>o</sub> = 160 to 1003 MHz                             | 15     |              | –    |       |
|                             | f <sub>o</sub> = 1003 to 1218 MHz                            | 15     |              | –    |       |
| Noise Figure                | f <sub>o</sub> = 50 to 1218 MHz                              | –      | 3.0          | 5.0  | dB    |
| Attenuator Range            | Attenuator Voltage 0V to 12V                                 | 0 - 20 |              |      | dB    |
| Power Enable/Disable        | Logic high (3.3V) applied to power enable pin <sup>[2]</sup> |        | Amp enabled  |      |       |
| Power Enable/Disable        | Logic low (0V) applied to power enable pin <sup>[3]</sup>    |        | Amp disabled |      |       |
| Thermal Resistance          | Junction to Mounting Base                                    |        | 6.5          |      | K/W   |

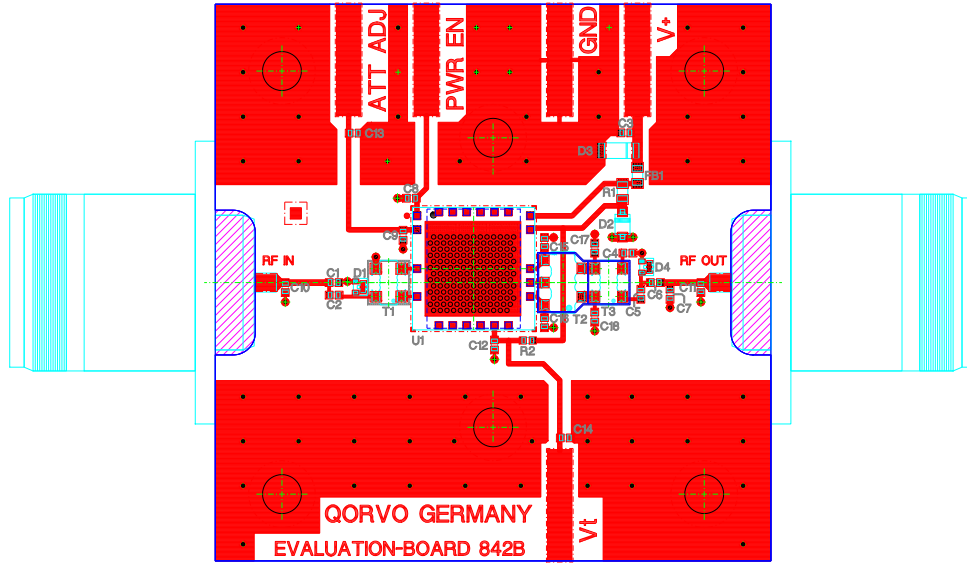
## Electrical Specifications – part 2

| Parameter   | Conditions (V+=12V, TMB=30°C, ZS=ZL=75Ω, ATT=0dB)  | Min | Typ | Max | Units |
|---|--|-----|-----|-----|-------|
| Adjacent Channel Power Ratio (ACPR); N=4 contiguous 256QAM channels | Channel Power = 58 dBmV;<br>Adjacent channel up to 750 kHz from channel block edge, f= 50 to 1000 MHz                                    |     |     | -58 | dBc   |
|   | Channel Power = 58 dBmV;<br>Adjacent channel (750 kHz from channel block edge to 6 MHz from channel block edge), f= 50 to 1000 MHz       |     |     | -60 | dBc   |
|   | Channel Power = 58 dBmV;<br>Next-adjacent channel (6 MHz from channel block edge to 12 MHz from channel block edge), f= 50 to 1000 MHz   |     |     | -63 | dBc   |
|   | Channel Power = 58 dBmV;<br>Third-adjacent channel (12 MHz from channel block edge to 18 MHz from channel block edge), f= 50 to 1000 MHz |     |     | -65 | dBc   |
| 2 <sup>nd</sup> Order Harmonic (HD2);<br>N=1 256QAM channel         | Channel Power = 66 dBmV;<br>In each of 2N contiguous 6 MHz channels coinciding with 2nd harmonic components (up to 1000MHz)              |     |     | -63 | dBc   |
| 3 <sup>rd</sup> Order Harmonic (HD3);<br>N=1 256QAM channel         | Channel Power = 66 dBmV;<br>In each of 3N contiguous 6 MHz channels coinciding with 3rd harmonic components (up to 1000MHz)              |     |     | -63 | dBc   |
| CTB   | Vo=48 dBmV, flat, 79 analog channels<br>plus 75 digital channels (-6dB offset) <sup>[4]</sup>  |     | -73 |     | dBc   |
| XMOD  |  |     | -70 |     | dBc   |
| CSO   |  |     | -75 |     | dBc   |
| CIN   |  |     | 64  |     | dB    |

1. The slope is defined as the difference between the gain at the start frequency and the gain at the stop frequency.
2. Logic high is defined as power enable voltage >2V
3. Logic low is defined as power enable voltage <0.4V
4. 79 analog channels, NTSC frequency raster: 55.25MHz to 547.25MHz, +48dBmV flat output level, plus 75 digital channels, -6dB offset relative to the equivalent analog carrier.

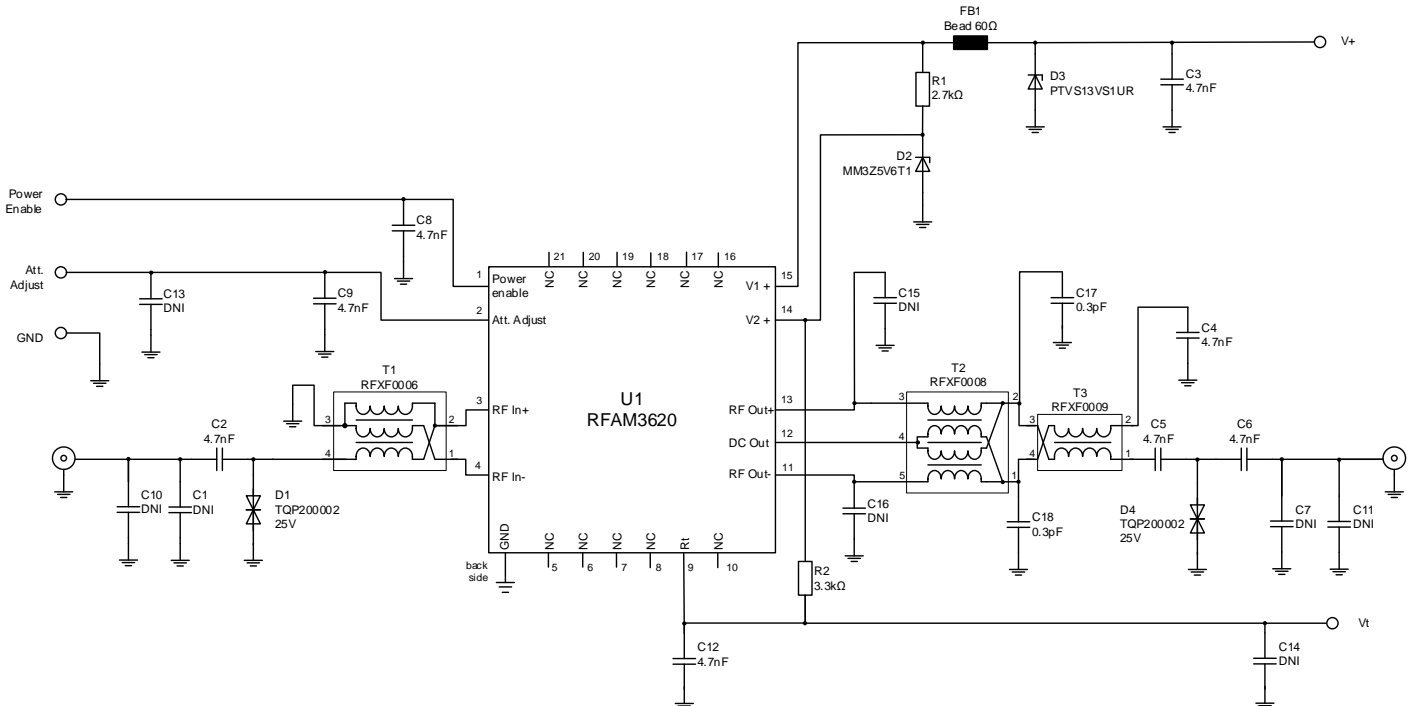
Composite Second Order (CSO) - The CSO parameter (both sum and difference products) is defined by ANSI/SCTE 6. Composite Triple Beat (CTB) The CTB parameter is defined by ANSI/SCTE 6. Cross Modulation (XMOD) - Cross modulation (XMOD) is measured at baseband (selective voltmeter method), referenced to 100% modulation of the carrier being tested. Carrier to Intermodulation Noise (CIN) - The CIN parameter is defined by ANSI/SCTE 17 (Test procedure for carrier to noise).

Evaluation Board Assembly Drawing



Note:  
 Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. A via drill diameter of 0.4mm and a minimum via wall copper plating thickness of 25um is recommended. Open vias are preferred to allow flux and gases to escape during reflow soldering and therefore to minimize voiding. Underneath this via array a heat sink with thermal grease needs to be placed which is able to dissipate the complete module DC power (up to 6.1 Watts). In any case the module backside temperature should not exceed 100 °C.

Evaluation Board Schematic

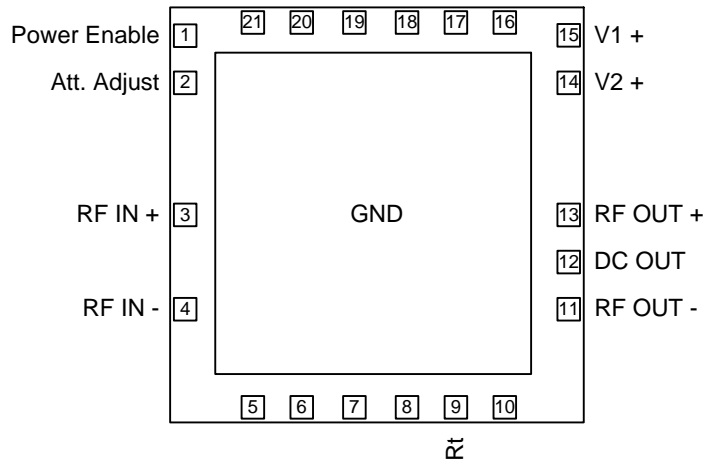


## Evaluation Board Bill of Materials (BOM)

| Reference Des.                  | Value          | Description   | Manuf.        | Part Number    |
|---------------------------------|----------------|---|---------------|----------------|
| PCB                             | Rev B          | PCB RFAM3620 – EVB 842B   | Qorvo         |                |
| C1, C7, C10, C11, C15, C16      | DNI            | optional to improve matching in application                               |               |                |
| C2, C3, C4, C5, C6, C8, C9, C12 | 4.7 nF         | CAP, 0402, 10%, 50V, X7R  |               |                |
| C13, C14                        | DNI            | optional blocking CAP   |               |                |
| C17, C18                        | 0.3 pF         | CAP, 0402, $\pm 0.1$ pF, 50V, C0G   |               |                |
| R1                              | 2.7 k $\Omega$ | RES, 0402, 1%, TK100  |               |                |
| R2                              | 3.3 k $\Omega$ | RES, 0402, 1%, TK100  |               |                |
| FB1                             | 60 $\Omega$    | Impedance Bead, 0603, 60 $\Omega$ @ 100MHz, LM, DCR 0.10 $\Omega$ , 800mA | TaiyoYuden    | BK 1608 HS 600 |
| D1, D4                          | 25 V           | ESD Protection Diode TQP200002, TSLP3                                     | Qorvo/ Unisem | TQP200002      |
| D2                              | 5.6 V          | Zener Diode MM3Z5V6T1G, SOD-323   | ON Semi       | MM3Z5V6T1G     |
| D3                              | 13 V           | Diode, TVS, PTVS13VS1UR, SOD123W  | NXP           | PTVS13VS1UR    |
| T1                              |                | RFXF0006  | Qorvo         |                |
| T2                              |                | RFXF0008  | Qorvo         |                |
| T3                              |                | RFXF0009  | Qorvo         |                |
| U1                              | DUT            | RFAM3620  | Qorvo         |                |

Notes:

## Pin Configuration



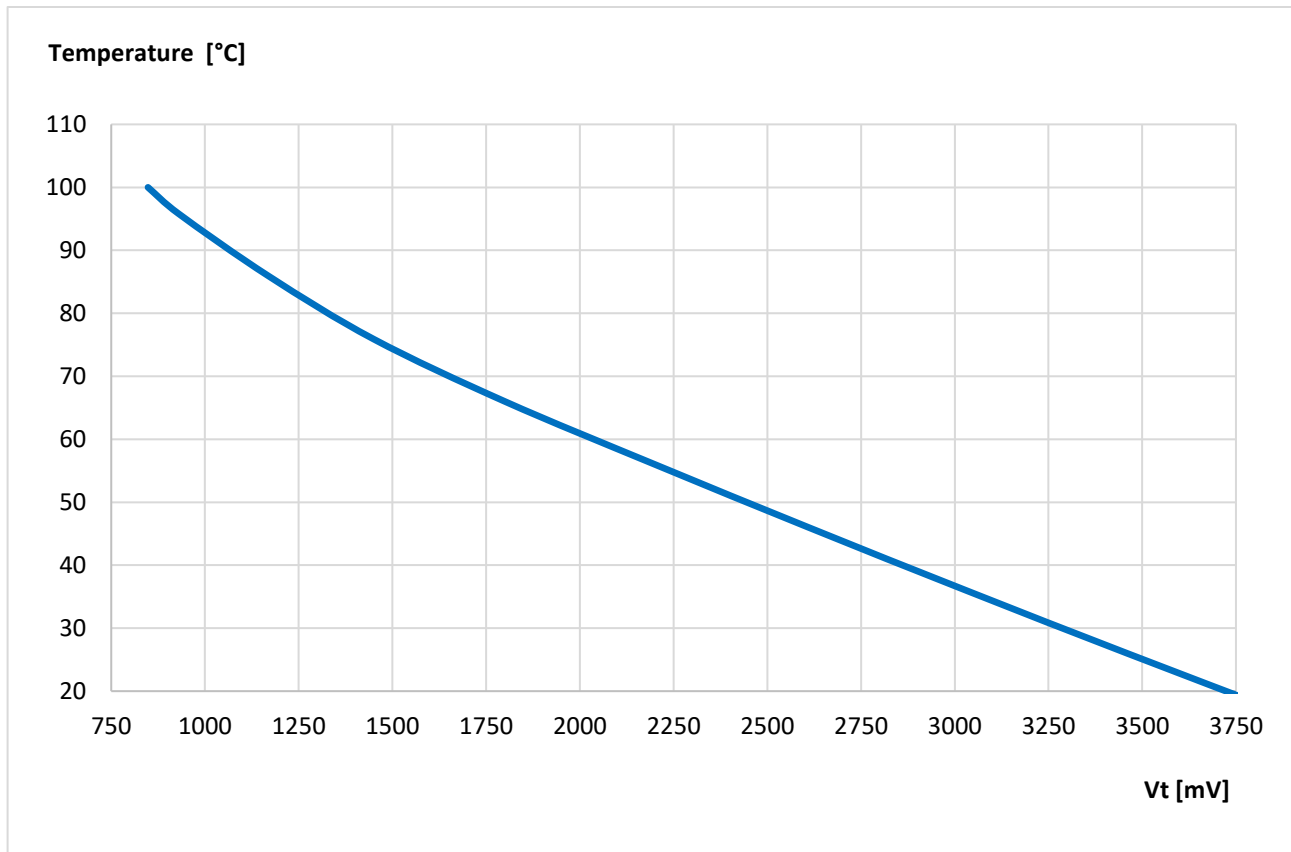
## Pin Description

| Pin No. | Label        | Description                             |
|---------|--------------|---|
| 1       | Power Enable | Logic Level (3.3V) Power Enable Control |
| 2       | Att. Adjust  | Voltage Adjustable Attenuator           |
| 3       | RF IN (+)    | RF AMP Positive Input                   |
| 4       | RF IN (-)    | RF AMP Negative Input                   |
| 5 - 8   | N.C.         |   |
| 9       | Rt           | NTC Output for Temperature Sensing      |
| 10      | N.C.         |   |
| 11      | RF OUT (-)   | RF AMP Negative Output                  |
| 12      | DC Out       | 12V Output                              |
| 13      | RF OUT (+)   | RF AMP Positive Output                  |
| 14      | V2 +         | Supply Voltage 5.6V                     |
| 15      | V1 +         | Supply Voltage 12V                      |
| 16 - 21 | N.C.         |   |

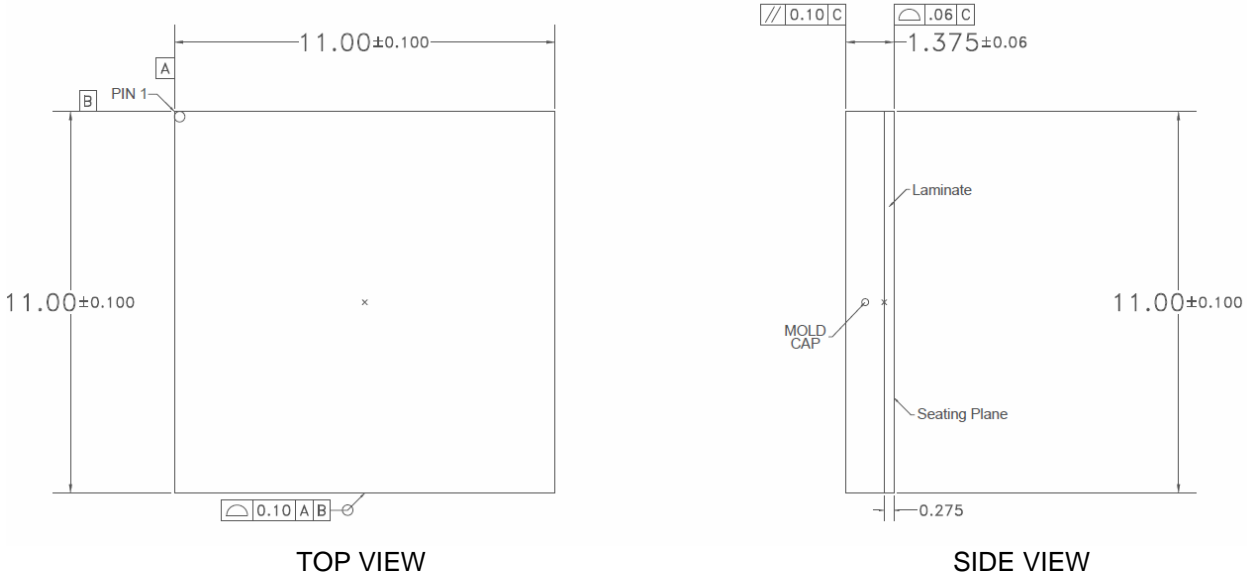
## RFAM3620 Temperature Sensing Feature

The RFAM3620 provides an internal NTC resistor for temperature sensing. This resistor is located right next to the output transistor stage. Within the application circuit the NTC is part of a voltage divider. The output voltage of the voltage divider ( $V_t$ ) can be correlated to the module backside temperature.

### Module Backside Temperature versus $V_t$ (typical values)

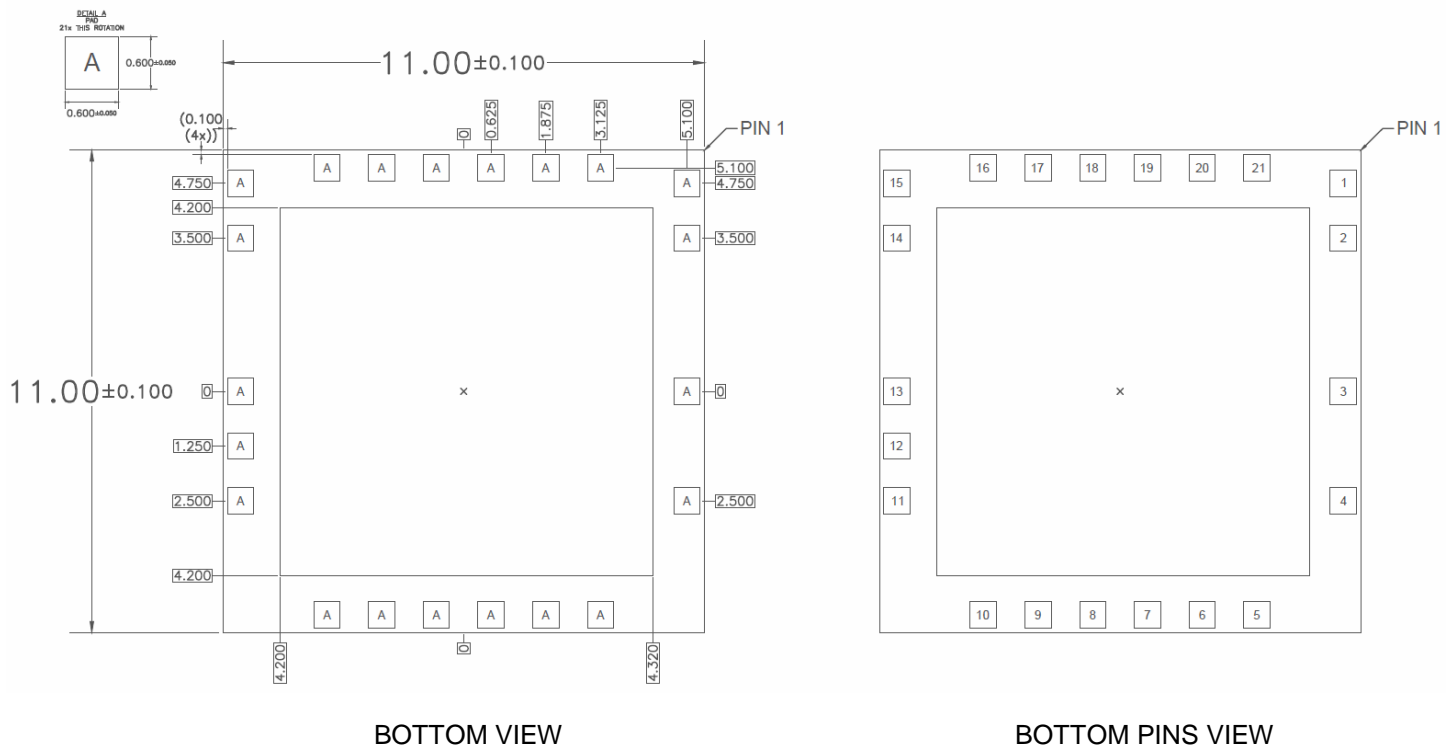


Package Outline Drawing (Dimensions in millimeters)



TOP VIEW

SIDE VIEW



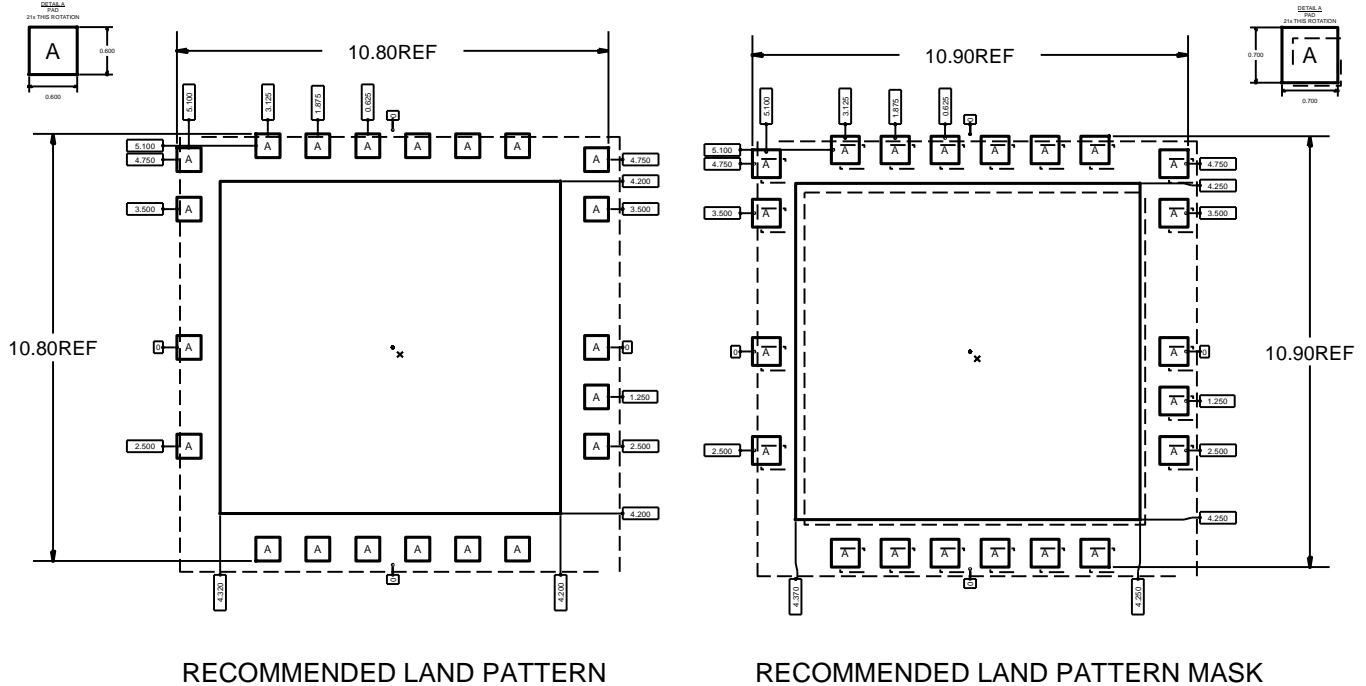
BOTTOM VIEW

BOTTOM PINS VIEW

Notes:

1. Dimension and tolerance formats conform to ASME Y14.5M-1994.
2. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
3. Co-planarity applies to the exposed ground/thermal pad as well as the contact pins.
4. Package body length/width does not include plastic flash protrusion across mold parting line.

PCB Metal Land Pattern (Dimensions in millimeters)



- Notes:
1. All dimensions are in millimeters. Angles are in degrees.
  2. Use 2 oz. copper minimum for top and bottom layer metal.
  3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.10").
  4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.
  5. Place mounting screws near the part to fasten a back side heat sink.
  6. Do not apply solder mask to the back side of the PC board in the heat sink contact region.
  7. Ensure that the backside via region makes good physical contact with the heat sink.

## Handling Precautions

| Parameter                        | Rating  | Standard                   |
|----------------------------------|---------|----------------------------|
| ESD – Human Body Model (HBM)     | 1B      | ANSI/ESD/JEDEC JS-001-2012 |
| ESD – Charged Device Model (CDM) | C3      | JEDEC JESD22-C101F         |
| MSL – Moisture Sensitivity Level | Level 3 | IPC/JEDEC J-STD-020        |



Caution!  
ESD-Sensitive Device

## Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes. Solder profiles available upon request.

Contact plating: NiPdAu

## RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

## Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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